

## TITLE OF THE INVENTION

Electric Field Directed Construction of Diodes Using  
Free-Standing Three-Dimensional Components

## CROSS-REFERENCE TO RELATED APPLICATIONS

5 The application claims priority from U.S. Provisional Application  
No. 60/101,363, filed September 22, 1998, and is a continuation-in-part of co-  
pending U.S. Patent Application No. 09/061,818, filed April 16, 1998, <sup>now Patent No. 6,120,669,</sup> the latter  
corresponding to International Patent Application No. PCT/US98/07699, filed April  
16, 1998 and published under International Publication No. WO/98/46810, on  
10 October 22, 1998. U.S. Patent Application No. 09/061,818 claims the benefit of  
U.S. Provisional Application No. 60/043,265, filed April 16, 1997, U.S. Provisional  
Application No. 60/048,475, filed June 3, 1997, U.S. Provisional Application No.  
60/066,905, filed November 14, 1997, and U.S. Provisional Application No.  
60/079,722, filed March 27, 1998. The disclosures of all of these related  
15 applications are hereby incorporated herein by reference.

## BACKGROUND OF THE INVENTION

002250-1259/560  
The metallization of semiconductors using an electrodeposition  
strategy is undergoing a tremendous renewal of interest, fueled by the recent  
success in utilizing copper interconnects in microchip fabrication. Copper is well  
20 suited as a replacement for the currently used aluminum principally due to its lower  
electrical resistivity and superior electromigration properties. Electrodeposition as  
a copper metallization strategy has been shown to offer significant advantages in  
terms of cost and ease of handling over other currently used metallization  
techniques such as evaporation, sputtering or chemical vapor deposition. A major  
25 advantage is that electrodeposition is a wet process and does not require vacuum  
conditions. Typically, a lithographic process is used to localize the copper deposit  
on the semiconductor surface, determined by the selective removal of a photoresist  
exposed to illumination through a patterned mask. Other approaches for metal  
patterning of surfaces have been explored involving scanning tunneling  
30 microscopy, imprint technologies or resistless patterning using  
photoelectrodeposition, ion-bombardment or localized thermal plating. However,

in general, such approaches are only applicable to wiring on extremely flat and contiguous surfaces and usually require some type of contact or near contact with the semiconductor surface.

Copending U.S. Patent Application No. 09/061,818 described a novel technology which allows for the formation of electrical connections between isolated metal components. The method is based on the coupled electrodisolution and electrodeposition between two components in line with an electric field and is referred to as spatially coupled bipolar electrochemistry (sometimes hereinafter referred to as "SCBE"). A particular advantage of the method is that distances comparable in scale to the components involved can be spanned. This is in sharp contrast with conventional electrodeposition metallization strategies of semiconductors, which are limited either to the creation of thin films or the filling of templates.

The present invention is a novel extension of the technology of U.S. Patent Application No. 09/061,818 into making more devices not only in three dimensions using toposelective SCBE, but also into using the process for making electric current rectifying devices (diodes) by controlling the parameters of the SCBE process in a manner never thought of before. It was surprising that diodes would be formed using this process.

#### BRIEF SUMMARY OF THE INVENTION

One aspect of the present invention relates to a process of making an electric current rectifying device using spatially coupled bipolar electrochemical deposition comprising: (a) placing a source of electrically conductive material and at least two electrically conductive substrates and at least one semiconductor into an environment capable of conducting electricity and containing electrodes; (b) aligning the substrates and the semiconductor with respect to the electrodes such that the electrodes are not in contact with the substrates or the semiconductor and such that the material will form a conductive structure between and in contact with the substrates and the semiconductor when an electric field is applied between the electrodes; (c) applying a voltage to the electrodes to create a first electric field of a sufficient strength between the electrodes and for a time sufficient to form a first electrically conductive structure between and in contact with a first of the substrates

and the semiconductor, the electrically conductive structure being substantially aligned with the first electric field; (d) reversing the polarity of the voltage applied to create a second electric field of a sufficient strength between the electrodes and for a time sufficient to form a second electrically conductive structure between and in contact with a second of the substrates and the semiconductor, the electrically conductive structure being substantially aligned with the second electric field; the semiconductor thus being transformed into the rectifying device.

Another aspect of the present invention relates to a process of making an electric current rectifying device using spatially coupled bipolar electrochemical deposition comprising: (a) placing at least two electrically conductive substrates comprising sources of electrically conductive material and at least one semiconductor into an environment capable of conducting electricity and containing electrodes; (b) aligning the substrates and the semiconductor with respect to the electrodes such that the electrodes are not in contact with the substrates or the semiconductor and such that the material will form a conductive structure between and in contact with the substrates and the semiconductor when an electric field is applied between the electrodes; (c) applying a voltage to the electrodes to create a first electric field of a sufficient strength between the electrodes and for a time sufficient to form a first electrically conductive structure between and in contact with a first of the substrates and the semiconductor, the electrically conductive structure being substantially aligned with the first electric field; (d) reversing the polarity of the voltage applied to create a second electric field of a sufficient strength between the electrodes and for a time sufficient to form a second electrically conductive structure between and in contact with a second of the substrates and the semiconductor, the electrically conductive structure being substantially aligned with the second electric field; the semiconductor thus being transformed into the rectifying device.

#### BRIEF DESCRIPTION OF THE DRAWINGS

The foregoing summary, as well as the following detailed description of the invention, will be better understood when read in conjunction with the appended drawings. For the purpose of illustrating the invention, there are shown in the drawings embodiment(s) which are presently preferred. It should be

understood, however, that the invention is not limited to the precise arrangements and instrumentalities shown. In the drawings:

FIGS. 1A-1H,  
Figure 1, comprising, is a schematic representation of the formation of a rectifying device using (SCBE) according to the present invention. The distances are not drawn to scale.

, comprising FIGS. 2A-2L,  
Figure 2, are graphs depicting current (along the ordinate, in mA) vs. voltage (along the abscissa, in volts) characterizations of twelve samples of diodes prepared according to the present invention using the experimental design shown in Figure 1, using a field intensity of 500 V/cm (electrode distance 2.0 cm) and a duration of 30 minutes for each wire growth.

Figure 3 comprises images of micrographs 3A-3D showing various stages and details of the formation of a typical rectifying device made using the present invention. Figures 3A and 3B are top plan views with scale bars for indicating relative size and distance. Figures 3C and 3D are edge views of the silicon chips as shown in Figures 3A and 3B taken at a 45° angle. The vertical and horizontal scale bars are asymmetrical because the view along the edges in Figures 3C and 3D is at the indicated angle.

#### DETAILED DESCRIPTION OF THE INVENTION

The present invention extends the formation of electrical contacts between components using electric fields from typically, but not necessarily only two components to typically, but not necessarily only three components, wherein at least one component, which is typically the central component, is a semiconductor, instead of a metal substrate, and wherein more than one field direction can be used, for example by growing two separate connections onto a central semiconductor component by using two different electric field vectors. In a preferred embodiment, contacts made between the semiconductor and the metallic substrates components are not equal, which permits the creation of diodes. Furthermore, the order in which the electric fields are applied controls the direction in which current will flow most easily in the resulting diode.

More particularly, in a preferred embodiment, the present invention uses spatially coupled bipolar electrochemistry (SCBE) to form electrical connections between isolated copper and homogeneously doped silicon structures.

The technique is based on the spatially coupled electro-dissolution from the copper component and subsequent electrodeposition onto the silicon chip caused by the application of an electric field in a highly resistive medium. When interconnects are formed between a central silicon chip and two copper structures positioned on opposite sides, an asymmetry ensues which results in the formation of a rectifying device, with the forward bias direction controlled by the order in which the connections are formed. The principal mechanism of rectification appears to be dominated by differences in contact areas caused by partial dissolution of copper at the metal-semiconductor interface of the first wire during the growth of the second wire. The ability to create and connect rectifying devices without using photolithography, templates or physical contact may lead to novel approaches to construct computational architectures, which are in principle not limited to planar surfaces.

The process of this invention is based on bipolar electrochemistry and many aspects are based on SCBE, which is best explained by example. When a pair of electrodissolvable substances, such as copper particles, rings or the like are exposed to an electric field, they become polarized, even if they are not contacted by the electrodes forming the anode and cathode. At sufficiently elevated electric fields, material resulting from electrodisolution of the electrodissolvable substance, such as copper, for example, from one particle aligned with the electrodes becomes spatially coupled via electrodeposition on the other particle aligned with the first particle and the electrodes, resulting in the formation of a conductor or wire between the particles. Even without direct contact between at least one electrode and the particle and preferably, without any contact between either of the electrodes and the particles, and further, without initial contact between the particles, spatial coupling occurs between the particles. Thus, it has been discovered that the electrochemical phenomena between the particles are governed solely by the electric fields generated between the electrodes. SCBE allows the growth of conductive structures on isolated components, where contact with either or both electrodes is not required, with the location of the growth of the conductive substance being controlled by the electric field direction, rather than by contact of the electrodes with either or both particles involved in the reaction.



The environment capable of conducting electricity is usually, but not exclusively, a liquid environment. Suitable environments include gases or even solids (*e.g.*, ice or porous substances) so long as they have a dielectric constant lower than the conductive substrates and semiconductor(s) and can solvate the electrodepositable substance in a form in which it can electrodeposit onto the conductive substrates and semiconductor(s) upon application of an electric field.

Preferably the environment is a liquid or gel having the characteristics for the environment set forth above. The liquid or gel may contain additives such as an acid to remove oxides, a surfactant to prevent adhesion of gas bubbles, such as hydrogen gas that may be evolved, or other beneficial and optional additives.

When the electrodepositable substance is pyrrole, then a compound which induces or enhances conductivity of the polypyrrole should be present, such as sodium para-toluenesulfonate, on the order of about 0.1 mM to about 10 mM.

The choice of the environment depends on the type of metal or other electroconductive or electrodepositable material or substance, and the substrates and semiconductors used. One skilled in the art would be able to determine which environment is suitable for the situation based on electrochemical qualities involved in electrodisolution and electrodeposition. For example, in the case of copper and silver, the preferred environment is an aqueous solution containing up to 1 mM acid, preferably sulfuric acid such as at a concentration of about 0.01 mM, and up to 0.1 mM surfactant, preferably a nonionic surfactant, or an organic solution, preferably an acetonitrile/toluene mixture containing up to about 80 vol % toluene, and most preferably, 100% acetonitrile.

The electrodes may be any electrically conductive material connected to a voltage source, preferably a material that does not electrodisolve in the environment of the process. Gold, platinum and graphite are the preferred electrode materials. There may be instances where electrodisolvable electrodes are desired, however, where it is desired to deposit electrode material on the substrates and semiconductor(s), for example.

The present invention uses SCBE methodology to create rectifying devices, preferably using homogeneously doped semiconductive material, such as silicon and conductive substrates such as copper rings separated by several hundred

micrometers. The process of the invention is shown schematically, initially with respect to Figure 1, comprising Figures 1A through 1H., which shows that two electrical connections are grown using SCBE onto the opposite corners of a square silicon chip.

5 With reference to Figure 1, and more particularly Figure 1A, there is shown two substrate particles exemplified by a first square copper ring 10 and a second square copper ring 12, each having a square outer periphery and a circular cental hole. It is not necessary that the substrates be in the form of rings. A semiconductor, exemplified by a silicon chip 14, is positioned between the copper  
10 rings. These components may be positioned and supported on a printed circuit board of any typical insulator construction.. The system is bathed in a suitable medium, such as acetonitrile with no supporting electrolyte, and two electrodes, generally identified by the numerals 16 and 18, such as platinum electrodes, are positioned at the opposite ends of the line of components, without making physical  
15 contact with any of the substrates 10 or 12 or the semiconductor 14.

The alignment of the electric field is achieved by appropriately aligning the substrates and semiconductor(s) with respect to the electrodes (or conversely, aligning the electrodes with respect to the substrates and the semiconductor(s)) and to the source of the substance or material to be  
20 electrodeposited (which as explained above, may be one or more of the substrates). In bipolar electrochemistry, the substance to be deposited is placed in alignment with the electric field vector between the cathode or negative electrode and the anode or positive electrode such that the electrodeposition takes place in a direction from the cathode to the anode. Thus, very site-selective electrodeposition can be  
25 achieved without contacting the substrate in any way with the electrodes or without contacting the substrates or semiconductors in advance with the substance to be deposited.

Figure 1B depicts the situation when a voltage is applied across the platinum electrodes, where electrode 16B acts as an anode and electrode 16E acts as  
30 a cathode. This potential difference generates an electric field, which polarizes each component as shown. Copper electrodisolves from the anodically polarized region of the first copper ring 10 and the cuprous ions migrate to the cathodically polarized region of the silicon chip 14, where copper begins to electroplate in the



form of a wire 20. The wire-like deposit continues to grow until it reaches the first copper ring 10, as depicted in Figures 1C and D.

The voltage difference must be sufficient to create a field intensity sufficient to accomplish SCBE. Field intensity is dependent upon the smallest cross-sectional dimension of the substrates and semiconductor(s) aligned with the electric field. Substrates or semiconductors with smaller cross-sectional dimensions require a greater field intensity. One skilled in the electrochemistry art having read this disclosure could determine without undue experimentation the appropriate electric field and related process parameters to be used in various circumstances. For example and without limitation, where the substrates and semiconductor(s) have cross-sectional dimensions of about 2 mm, voltages that generate a field intensity of at least about 10 V/cm should be adequate to induce the electrochemical processes necessary for SCBE to be operative. A preferred field intensity for this size of the substrates and semiconductor(s) is about 500 V/cm.

As shown in Figure 1E, the field polarity is reversed, such that the electrode 18E becomes the anode and the electrode 16E becomes the cathode. The voltage is maintained and the process described above is repeated to grow a wire-like deposit 22 between the silicon chip 14 and the second copper ring 12. After immersing the components in an electroless copper plating solution, a rectifying device is generated with the rectification properties shown schematically in Figure 1H for n-Si. The direction of rectification would be opposite for p-Si or if the order of wire growth had been reversed.

The field should be applied for a time sufficient to allow for growth of the wires between the substrates and the semiconductor(s) using SCBE. The time is dependent both on the field intensity and the distance between the substrates and the semiconductor(s). Again by way of example and not limitation, when a field intensity of about 500 V/cm is applied to the system in which the substrates and semiconductor(s) have a cross-sectional dimension of about 2 mm and the space between each substrate and the semiconductor is about 0.5 mm, each of the wires grow in about 30 minutes.

The first connection is grown by applying an electric field in a direction favoring the electrodisolution of copper ions from the first copper ring 10 into the region facing the silicon chip 14. Since the corner of the chip exposed to

this liberated copper ion cloud is cathodically polarized, a ramified wire-like electrodeposit 20 grows from that corner until it reaches the first ring 10. When the direction of the electric field is reversed, preferably after rinsing the components and applying fresh electrically conductive medium, such as the acetonitrile for example, the same process is repeated on the opposite side of the silicon chip and a second deposit forms between the silicon chip 14 and the second copper ring 12.

As described previously in copending U.S. Patent Application 09/061,818, subsequent immersion of the system into an electroless plating bath ensures a solid connection between the silicon and copper components. In this aspect, where the bipolar electrochemical environment is a liquid electrically conductive environment, the process further preferably comprises removing the components formed into a rectifier as described above, preferably drying the device and the circuit board on which the electrically conductive structure was formed to adhere the structure to the circuit board, and then electrolessly plating the same or a different electrically conductive material on the electrically conductive structure until a desired thickness of the electrically conductive structure is obtained.

The present invention will now be described in further detail with reference to the following specific, non-limiting Example.

Copper-silicon contacts are known to form blocking (Schottky) junctions for both n-type and p-type silicon. (Cros, A.; Muret, P. *Materials Science Reports* 8, 271 (1992)). Thus, an experiment was devised to measure the I-V (current-voltage) measurements as graphed in the graphs of Figure 2 between two copper substrates 10 and 12 connected through the central silicon chip 14 and to determine the reverse characteristics of each contact.

Twelve sample devices were constructed as explained above generally with respect to Figure 1. An exemplary arrangement and an exemplary device are shown in Figure 3. Silicon wafers were cut to form chips 14 of n-type Si with dimensions of 2.12 mm x 2.12 mm then mounted as shown in Figure 3A on a circuit board 26 and inserted into a hole 28 drilled into the circuit board. N-type Si was used for six samples and p-type Si was used for the other six samples. The n-type 100-cleaved silicon was P-doped with a resistivity of 1.3  $\Omega\text{cm}$ ; the p-type 100-cleaved silicon was B-doped with a resistivity of 4.9  $\Omega\text{cm}$ . Square copper rings 10 and 12 of approximately the same dimensions as the silicon chips were

formed and mounted on the circuit board 26 in the relationship and at the distances indicated in Figures 3A and 3B. All excess copper present on the board was removed by scratching with a sharp tool. The platinum electrodes are not shown.

The electrically conductive environment was acetonitrile distilled from CaH.

The wire growth was carried out under  $N_2$  by applying and maintaining for 30 min. a voltage differential of 1000 volts, given that the distance between the two electrodes is 2.0 cm, to create a field intensity of 500V/cm, first with the anode adjacent to but not in contact with the first copper ring 10. The solution was replaced before the field direction was switched. The procedure just described was repeated using the same parameters mentioned, except that the anode was adjacent to but not in contact with the second copper ring 12.

Immediately after completing the application of the field in the reverse direction, the samples were washed with distilled water then dried and put into an electroless copper plating solution (Technic<sup>TM</sup> EC-70) for 3 hr. at room temperature, and finally washed and dried again.

The current-voltage curves shown in Figures 2A-2L were measured with a 4145 Semiconductor Parameter Analyzer. Figures 2A - 2F are current-voltage curves obtained between the two copper rings for identical experiments using n-Si. For Figures 2G to 2L, p-Si was used. In Figures 2A through 2F, positive voltages refer to polarization of the first copper ring 10 where growth of the first wire, represented by wire 20, occurred. In Figures 2G through 2L, negative voltages refer to polarization of the second copper ring 12 where growth of the second wire, represented by wire 22, occurred.

Maximal rectification ratios in the range of 15-473 were found and are shown in the Table below, following the written description. The reverse bias of the Cu/n-Si interface corresponds to electron movement from the metal into the semiconductor, with the opposite being the case for the Cu/p-Si interface. Consequently, analysis of the I-V curves in Figure 2 indicates that, for both n- and p-doped Si, either a lower barrier or a larger contact area is found for the second contact (wire). Although both contacts are prepared using identical field intensities and duration, the graphs of Figure 2 reveals highly asymmetric I-V curves, reflecting large differences in the reverse characteristics of the two contacts.

The optical micrograph of a typical experiment shown in Figures 3C and 3D confirm the graphical data. Figure 3C is a scanning electron micrograph of the contact area where copper is deposited on the corner of first wire 20 grown on a typical silicon chip. Figure 3D is the same as Figure 3C, but shows the corner of the second wire growth 22. In Figures 3C and 3D, the bright areas in the center, designated by numerals 20 and 22, respectively, correspond to copper. The material 30 on the top left and right of the chips is an In-Ga alloy that was added for the independent measurements of each contact .

In general, Schottky barrier heights are best estimated using forward current-voltage (I-V) characteristics based on the thermionic-emission model. (Okumura, T.; Yamamoto, S.-I.; Simura, M. *Jpn. J. Appl. Phys.* 32, 2626 (1993)). Since only reverse bias information is obtained by contacting the two copper components, ohmic contacts were introduced by rubbing an In-Ga alloy at the other two corners to interrogate each copper contact separately. From the contact areas measured by SEM and the saturation current  $J_s$  obtained from the I-V data, the Schottky barrier heights  $\phi_B$  for the n-Si/Cu contacts were calculated and are reported in the Table. Values ranging from 0.61 eV to 0.75 eV are obtained, consistent with the range of values in the literature obtained using the same method of analysis for Cu/n-Si contacts measured from electroless deposition (0.62 eV reported in Lee, M.K.; Wang, H. D.; Wang, J.J. *Solid State Electronics*, 41, 695 (1997); 0.68 eV reported in Datta, A.K.; Ghosh, K.; Chowdhury, N.K.D.; Daw, A.N. *Solid State Electronics*, 23, 905 (1980)) or electrolytic deposition (0.69 eV reported in Ghosh, K.; Chowdhury, N.K.D. *Int. J. Electronics*, 54, 615 (1983); 0.58 eV reported in Singh, B.K.; Mitra, R.N.; Daw, A.N. *Indian J. Pure Appl. Phys.* 18, 368 (1980); 0.74 eV reported in Wurst, E.C.; Borneman, E.H. *J. Appl. Phys.* 28, 235 (1957)).

The large ideality factor ( $n > 1.5$ ) and the soft reverse characteristics suggest that interfacial oxide and/or non-uniform contacts contribute significantly to the I-V characteristics observed in the graphs of Figure 2. Irregular contacts such as those present in porous silicon/copper interfaces as reported by Wang, G.-S.; Peng, L.; Ma, Y.-R.; Fang, R.C. *Chin. Phys. Lett.* 14, 124 (1997), or by pinholes in oxide layers as reported by Kabushemeye, E.; van Meirhaeghe, R.L.; Laflere, W.H.; Cardon, F. *Semicond. Sci. Technol.* 4, 543 (1989), are known to produce large

ideality factors. Anodic oxidation, which is expected to occur in this system, is also known to create thick oxide layers which generate very large ideality factors (Okumura, T.; Yamamoto, S.-I.; Simura, M. *Jpn. J. Appl. Phys.* 32, 2626 (1993)).

The scanning electron micrographs revealed large differences  
5 between the areas of the first and second contacts (see the Table and Figures 3C and 3D), well in accord with the hypothesis that contact area is largely responsible for the trends observed in Figure 2. The origin of these differences was probed by measuring the apparent contact area on both sides of the chip, at each step of device construction. The most salient finding from these investigations is that the first  
10 contact is initially as large as the second, but becomes significantly reduced after the growth of the second wire (see the Table entries M-R). An explanation for this is that, during the growth of the second wire, the initially deposited copper electrodisolves at the silicon interface while that corner of the chip is anodically polarized. The electrodisolution appears to be limited to the Cu/Si interface  
15 leaving the path to the copper component intact. Subsequent electroless copper deposition treatment ensures proper contact between each copper ring and the silicon chip without significantly increasing the apparent contact area on both corners (compare the Table entries P-R and A-L). Such a mechanism supports the formation of contacts by SCBE at adjacent corners that would not show significant asymmetry in the resulting I-V curve, which is borne out by experiment (data not  
20 shown).

Although differences in contact area seem to account for the bulk of the behavior of the devices formed, other mechanisms may play a role. Indeed, under certain circumstances, such as the use of other metals and semiconductors, or  
25 at different scales and field intensities, such effects may become dominant. For example, it is possible that preferential migration of copper into the interfacial oxide at the second wire Cu/Si interface could contribute to the device asymmetry (Miyazaki, H.; Kojima, H.; Hinode, K. *J. Appl. Phys.* 81, 7746 (1997)). Another possible complication is electrochemical doping, which may involve penetration of  
30 copper ions into the semiconductor. Interstitial copper is known to be a donor in silicon and, although electromigration of copper within silicon has been used to create devices (Cahen, D.; Chernyak, L. *Adv. Mater.* 9, 861 (1997)), the effect is rather weak compared to the effect caused by the differences in contact areas.

However, in other systems, such as HgCdTe, electrochemical copper doping can be significant enough to lead to type conversion (Talasek, R.T.; Ohlson, M.J.; Syllaos, A.J. *J. Electrochem. Soc.* 133, 230 (1986)). This suggests that for other metal-semiconductor systems, device creation by type conversion may become the dominant effect.

The experiments discussed herein support a proof-of-principle demonstration of the present invention of creating rectifying devices by electrically connecting isolated semiconductor and metal structures without lithography or physical contact, using SCBE. Although the direct metallization of silicon with copper may prove to be unsuitable for many applications due to known problems of device degradation, the introduction of suitable diffusion barriers such as Ta or Si<sub>3</sub>N<sub>4</sub> (both as reported in Hu, C.-K.; Harper, J.M.E *Mater. Chem. Phys.* 52, 5 (1998)), or TiN (as reported by Li, J.; Mayer, J. W.; Shacham-Diamand, Y.; Colgan, E.G. *Appl. Phys. Lett.* 60, 2983 (1992)), should overcome such difficulties. Such a barrier may also enhance device properties by preventing the formation of interfacial oxide during anodic polarization.

Furthermore, since the electrolytic step of the process appears to serve principally to lay down a seed layer at the surface of the semiconductor, other choices for the electroless plating bath could be used to create arbitrary metal-semiconductor contacts varying from ohmic to strongly rectifying. In addition, the mechanism believed to be operating in the present system supports the reasonable belief that this technique should be applicable to many other semiconductors of current interest including GaAs, InP and CdS.

It will be appreciated by those skilled in the art that changes could be made to the embodiments described above without departing from the broad inventive concept thereof. It is understood, therefore, that this invention is not limited to the particular embodiments disclosed, but it is intended to cover modifications within the spirit and scope of the present invention as defined by the appended claims.

Table: Characterization of the rectifying devices

		Sample No.	SEM Contact Area of Wire 1 ( $\mu\text{m}^2$ )	SEM Contact Area of Wire 2 ( $\mu\text{m}^2$ )	Max. Rectification ratio	$-\phi_B$ (eV) Wire 1	$-\phi_B$ (eV) Wire 2	Ideality Factor(n) Wire 1	Ideality Factor(n) Wire 2
After Electroless Plating	n type Si	A	28 850	182 716	27	0.75	0.64	3.5	2.9
		B	14 610	224 989	47	0.64	0.63	3.9	3.8
		C	5 303	178 581	27	0.72	0.62	4.2	3.9
		D	6 629	307 555	168	0.69	0.69	1.9	2.6
		E	8 413	284 105	169	0.74	0.63	2.5	4.0
		F	365	183 082	184	0.66	0.61	2.6	3.8
	p type Si	G	14 600	87 700	15				
		H	43 100	349 000	473				
		I	19 600	329 000	474				
		J	44 900	280 000	108				
		K	34 400	317 000	22				
		L	42 800	199 000	322				
Before Plating	One wire Only	M	382 000						
		N	339 000						
		O	198 000						
	Both wires Grown	P	32 100	206 000					
		Q	8 800	126 000					
		R	46 800	175 000					